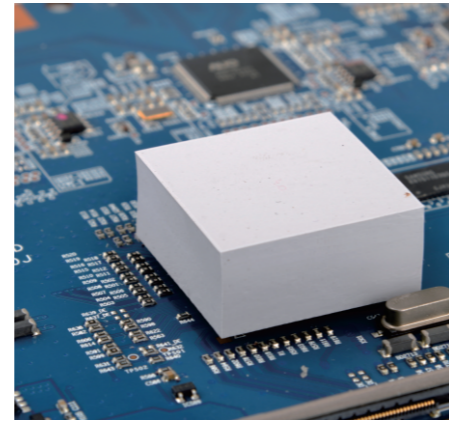


TP080 導熱硅膠墊片 Thermal Conductive Pad

TP080是一款具有高回彈性，有成本效益的導熱填縫墊片。具有良好的電氣絕緣特性，在-40°C~150°C可以穩定工作，滿足UL94V0的阻燃等級要求。

The TP080 series is a superior elastic and cost effective thermal conductive pad with excellent electrical isolated performance. It works stably at ambient temperature during -40-150 celcius with meeting the requirement of UL94V-0 class.



主要特性

- 導熱系數: 0.8 W/mK
- 低壓縮力應用
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 玻璃纖維加強
- 硬度有 18 Shore C 和 35 Shore C

MAIN CHARACTERISTICS

- Thermal Conductivity: 0.8W/m.k
- Low compressibility application
- Double side in natural inherent tack
- Excellent electrical isolation
- Exceptional temperature endurance
- Fiberglass reinforced
- Hardness: Shore C 18 or 35

APPLICATIONS

- PC、NB
- Chipsets
- Heat sinks DRAM DVD
- Game machine Set-Top Box
- LED lighting
- Wireless Hub Telecommunication
- Flat Panel Display(LCD、PDP...)
- Automotive modules
- Solar inverter

典型應用

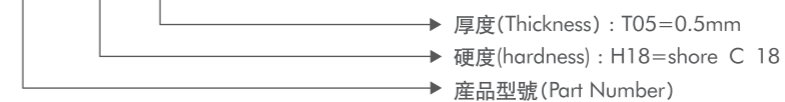
- 低導熱要求的電源模塊
- 平面顯示器
- 記憶存儲模塊
- 功率轉換設備
- LED照明設備
- PDP顯示屏
- LCD背光模塊
- 電磁爐等半導體發熱模
- 太陽能逆變器

TP080 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP080-T03	TP080-T05	TP080-T10	TP080-T20	TP080-T30	TP080-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.3	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	灰白色	灰白色	灰白色	灰白色	灰白色	灰白色	Visuai
硬度 Hardness (Shore C)	40	30±5	18±5	18±5	18±5	18±5	ASTM D2240
密度 Density (g/cm ³)	2.2	2.2	2.2	2.2	2.2	2.2	ASTM D792
撕裂強度 Tear strength (KN/m)	0.2	0.80	0.80	0.80	0.70	0.70	ASTM D412
延伸率 Elongation (%)	100	132	135	134	143	146	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	5.4	6.5	8	> 10	> 10	> 10	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	ASTM D257
介電常數 Dielectric constant (@1 MHz)	3.5	4.51	4.51	4.51	4.51	4.51	ASTM D150
重量損失 Weight loss (%)	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	0.8	0.8	0.8	0.8	0.8	0.8	ASTM D5470

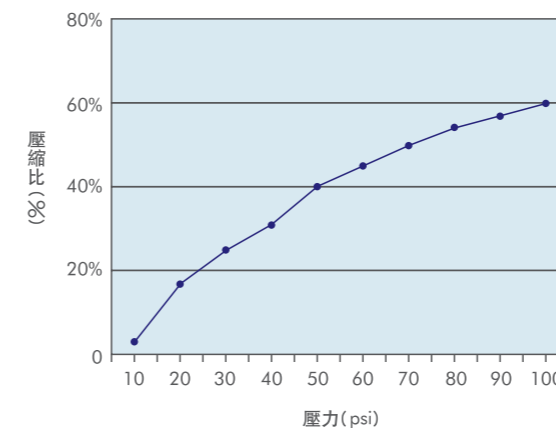
料號編碼原則 (Part Number Code) :

TP080/H18-T05

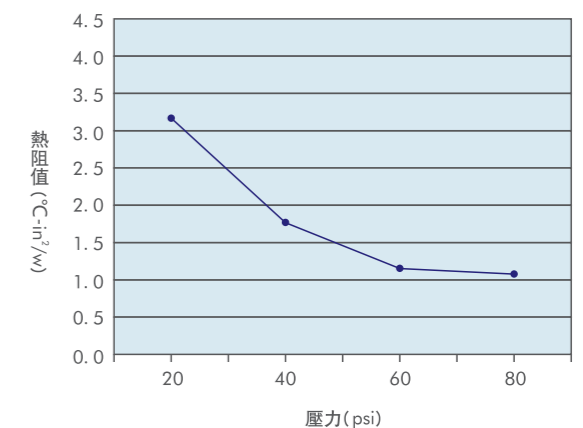


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions)

TP080/H35-T20形變量與壓力關係圖



TP080/H35-T20熱阻與壓力關係圖



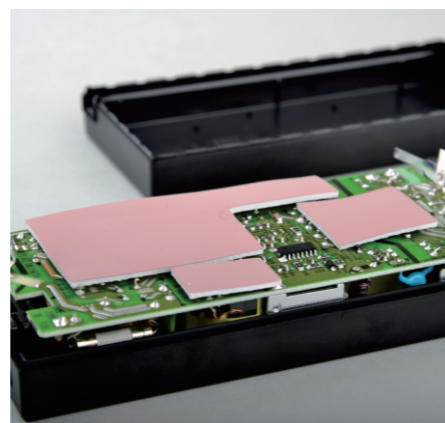
UTP100 導熱硅膠墊片 Thermal Conductive Pad

UTP100系列導熱硅膠墊片,是使用硅膠與導熱陶瓷填料,以玻璃纖維布為補強材料,經由特殊工藝加工而成。是一款非常柔軟,具有優異的可壓縮性,可與電子元器件緊密接觸,有效降低界面熱阻,表現極佳的導熱性能。

UTP100系列導熱硅膠墊片,具單面自粘性,在-40°C~150°C可以穩定工作,同時滿足UL94V0等級阻燃要求。

The UTP100 series is made through advanced artificial handling with fiberglass reinforced, which is composed of silicone polymer with ceramic fillers backed thermal conductive pad. The UTP100 is an ultra-soft and exceptional compressive material. It offers excellent thermal performance in close contact with electronic components for effectively lowering the interface thermal resistance.

It has natural inherent tacky on one side, and works stably at ambient temperature during -40-150 celcius with meeting the requirement of UL94V-0 class.



主要特性

- 導熱系數: 1.0W/mK
- 超柔軟, 高壓縮性, 可至50%
- 單面自粘
- 玻纖布增強材料強度, 可衝孔不變形
- 防刺穿
- 高電氣絕緣

典型應用

- 高電氣絕緣要求的MOS管
- 冷卻器件到底盤或框架之間
- 高速大存儲驅動
- 平面顯示器
- 記憶存儲模塊
- 功率轉換設備
- LED照明設備

MAIN CHARACTERISTICS

- Thermal Conductivity: 1.0W/m.k
- Ultra-soft with exceptional compressibility to 50%
- Single side in natural inherent tack
- Fiberglass reinforced without deforming in die-cut
- Cut-through resistance
- Excellent electrical isolation

APPLICATIONS

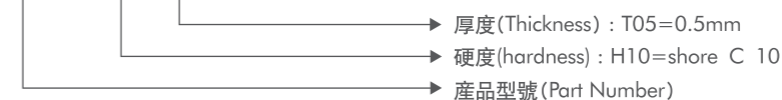
- Highly electrical isolated MOSFET
- Computer and peripherals
- Telecommunications
- Between heat-generating semiconductors or magnetic components
- a heat sink
- Area where heat needs to be transferred to a frame, chassis
- type of heat spreader

UTP100 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	UTP100-T05	UTP100-T10	UTP100-T20	UTP100-T30	UTP100-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&玻纖	硅膠&玻纖	硅膠&玻纖	硅膠&玻纖	硅膠&玻纖	—
顏色 Color	白色&棕紅色	白色&棕紅色	白色&棕紅色	白色&棕紅色	白色&棕紅色	Visuai
硬度 Hardness (Shore C)	10±5	10±5	10±5	10±5	10±5	ASTM D2240
密度 Density (g/cm ³)	2.0	2.0	2.0	2.0	2.0	ASTM D792
撕裂強度 Tear strength (KN/m)	2.5	2.5	2.5	2.5	2.5	ASTM D412
延伸率 Elongation (%)	60	60	60	60	60	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	6.3	7.2	9.1	≥10	≥10	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	1.5×10 ¹⁶	ASTM D257
介電常數 Dielectric constant (@1 MHz)	5.37	5.37	5.37	5.37	5.37	ASTM D150
重量損失 Weight loss (%)	< 0.3	< 0.3	< 0.3	< 0.3	< 0.3	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	1.0	1.0	1.0	1.0	1.0	ASTM D5470

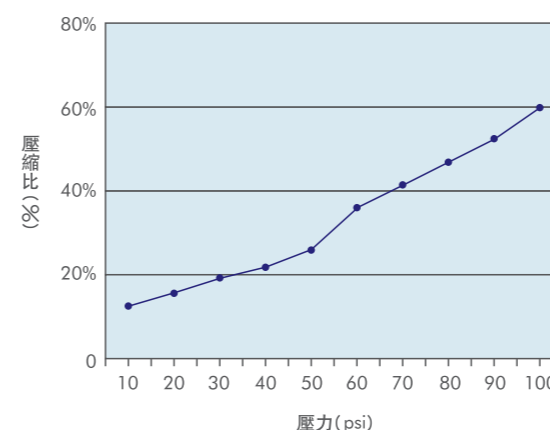
料號編碼原則 (Part Number Code) :

UTP100/H10-T05

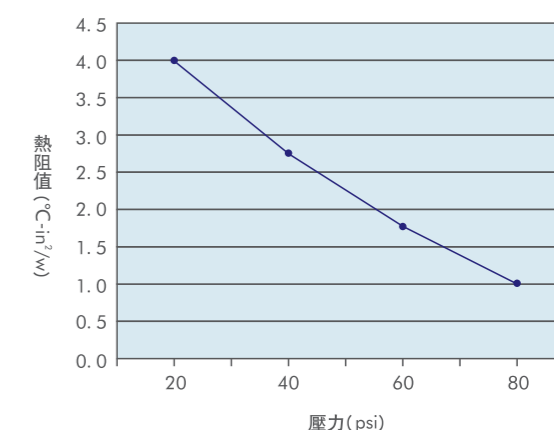


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions)

UTP100/H10-T20 形變量與壓力關係圖



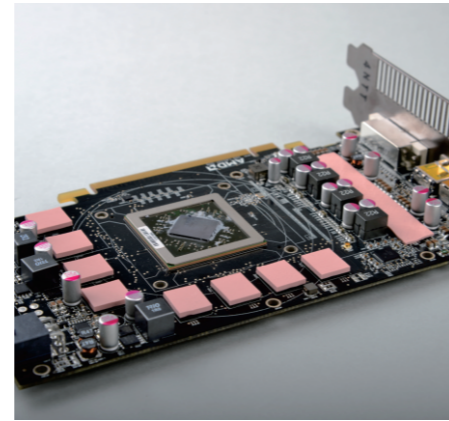
UTP100/H10-T20 熱阻與壓力關係圖



TP120 導熱硅膠墊片 Thermal Conductive Pad

TP120是一款針對低壓縮力，低熱阻，高柔軟和順從性應用而開發的一款獨特的導熱墊片。在-40°C~150°C可以穩定工作，同時滿足UL94V0等級阻燃要求。

The TP120 series is a ultra soft and highly conformable thermal conductive pad, which is recommended for application on low compression and low thermal resistance. It works stably at ambient temperature during -40-150 celcius with meeting the requirement of UL94V-0 class.



主要特性

- 導熱系數: 1.2W/mK
- 低壓縮力應用
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 低揮發性 (D3-D20)

典型應用

- 筆記本和臺式電腦顯卡與散熱器之間
- 冷卻器件到底盤或框架之間
- 高速大存儲驅動
- 汽車發動機控制單元
- 平面顯示器
- 功率轉換設備
- LED照明設備
- PDP顯示屏
- LCD背光模塊

MAIN CHARACTERISTICS

- Thermal Conductivity: 1.2W/m.k
- Low Compression application
- Double side in natural inherent tack
- Excellent electrical isolation
- Superior Temperature endurance
- Low volatile performance (D3-D20)

APPLICATIONS

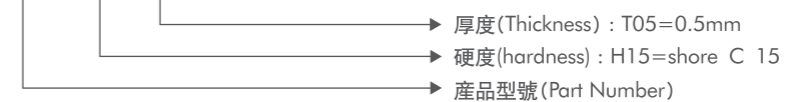
- Computer and peripherals
- Power conversion
- Chip scale packages
- RDRAM memory modules
- Telecommunications
- Area where heat needs to be transferred to a frame
- LED lighting
- chassis, or other type of heat spreader
- Flat Panel Display (LCD, PDP, ...)

TP120 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP120FG-T025	TP120-T05	TP120-T10	TP120-T20	TP120-T30	TP120-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.25	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	淺紅色	淺紅色	淺紅色	淺紅色	淺紅色	淺紅色	Visual
硬度 Hardness (Shore C)	35	15±5	15±5	15±5	15±5	15±5	ASTM D2240
密度 Density (g/cm ³)	2.3	2.3	2.3	2.3	2.3	2.3	ASTM D792
撕裂強度 Tear strength (KN/m)	1.2	1.0	1.0	1.0	1.0	1.0	ASTM D412
延伸率 Elongation (%)	50	50	50	50	50	50	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	5.5	7	7	7	7	7	ASTM D149
介電常數 Dielectric constant (@1 MHz)	3.0	5.0	5.0	5.0	5.0	5.0	ASTM D150
重量損失 Weight loss (%)	<0.5	<0.5	<0.5	<0.5	<0.5	<0.5	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m-K)	1.2	1.2	1.2	1.2	1.2	1.2	ASTM D5470

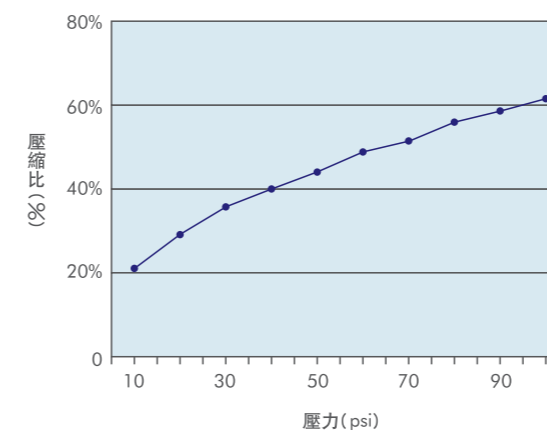
料號編碼原則 (Part Number Code) :

TP120/H15-T05

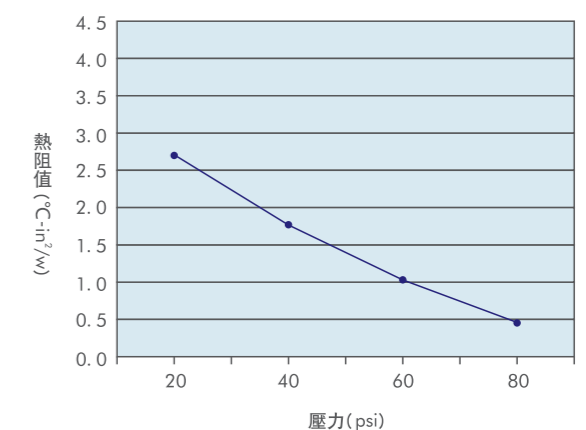


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

TP120/H15-T20形變量與壓力關係圖



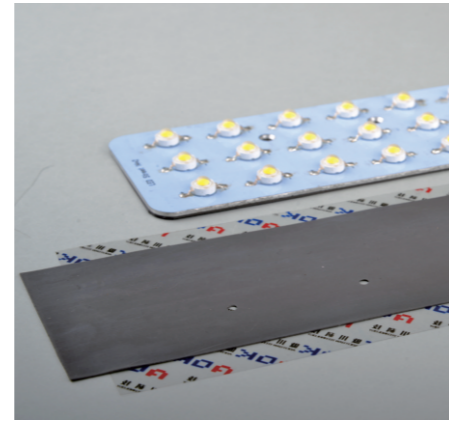
TP120/H15-T20熱阻與壓力關係圖



TP150 導熱硅膠墊片 Thermal Conductive Pad

TP150是一款性價比極高的導熱填縫墊片，雙面自粘，容易裝配。在-40°C ~150°C 可以穩定工作，同時滿足UL94V0等級阻燃要求。

The TP150 series is a remarkable cost effective thermal conductive pad. It is in double side natural inherent tack and easy assembly. It works stably at ambient temperature during -40-150 celcius with meeting the requirement of UL94V-0 class.



主要特性

- 導熱系數: 1.5W/mK
- 低壓縮力應用
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 容易裝配，可重複使用

典型應用

- 計算器散熱模塊
- 冷卻器件到底盤或框架之間
- 高速大存儲驅動
- 汽車發動機控制單元
- 平面顯示器
- 功率轉換設備
- LED照明設備
- PDP顯示屏
- LCD背光模塊

MAIN CHARACTERISTICS

- Thermal Conductivity: 1.5W/m.k
- Low Compression application
- Double side in natural inherent tack
- Excellent electrical isolation
- Superior Temperature endurance
- Easy in assembly and reusable

APPLICATIONS

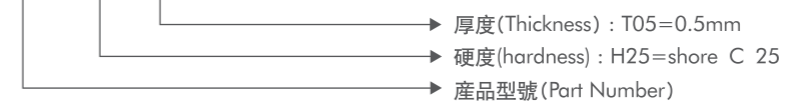
- Computer and peripherals
- Power conversion
- Chip scale packages
- RDRAM memory modules
- Telecommunications
- Area where heat needs to be transferred to a frame
- LED lighting
- chassis, or other type of heat spreader
- Flat Panel Display(LCD、PDP、...)

TP150 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP150FG-T025	TP150-T05	TP150-T10	TP150-T20	TP150-T30	TP150-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.25	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	深灰色	深灰色	深灰色	深灰色	深灰色	深灰色	Visual
硬度 Hardness (Shore C)	45	30±5	25±5	25±5	25±5	25±5	ASTM D2240
密度 Density (g/cm ³)	2.5	2.5	2.5	2.5	2.5	2.5	ASTM D792
撕裂強度 Tear strength (KN/m)	0.88	0.46	0.47	0.47	0.47	0.48	ASTM D412
延伸率 Elongation (%)	70	70	73	74	75	77	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	5.1	5.2	7.0	>10	>10	>10	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	8×10 ¹⁶	8×10 ¹⁶	8×10 ¹⁶	8×10 ¹⁶	8×10 ¹⁶	8×10 ¹⁶	ASTM D257
介電常數 Dielectric constant (@1 MHz)	3.2	5.75	5.75	5.75	5.75	5.75	ASTM D150
重量損失 Weight loss (%)	<0.3	<0.3	<0.3	<0.3	<0.3	<0.3	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	1.5	1.5	1.5	1.5	1.5	1.5	ASTM D5470

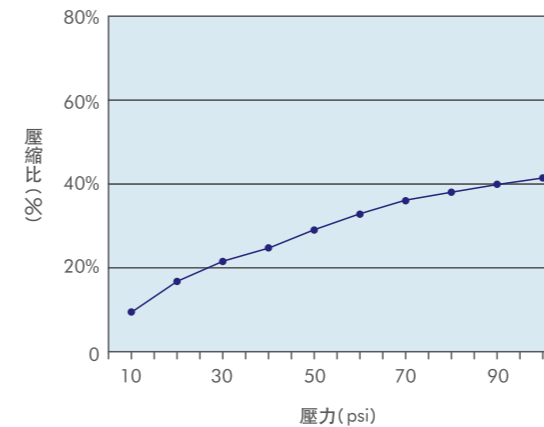
料號編碼原則 (Part Number Code) :

TP150/H25-T05

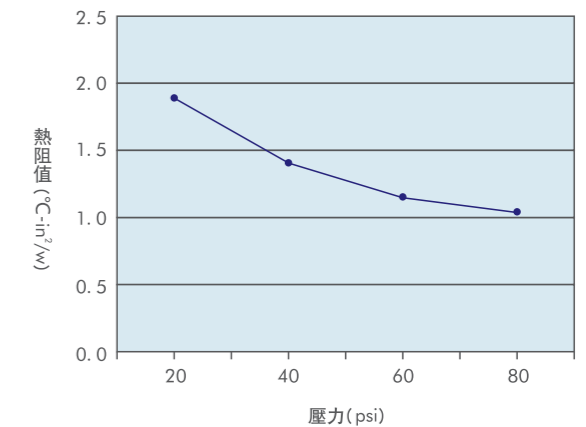


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強，產品名稱以“FG”后綴。

TP150/H25-T20形變量與壓力關係圖



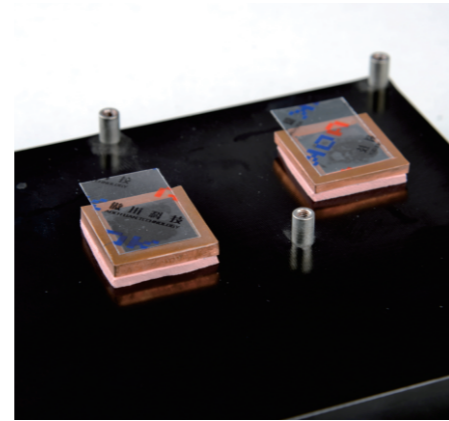
TP150/H25-T20熱阻與壓力關係圖



TP200 導熱硅膠墊片 Thermal Conductive Pad

TP200系列導熱硅膠墊片,是使用硅膠與導熱陶瓷填料經由特殊工藝加工而成,性價比極高,雙面自粘,低壓縮力下表現出良好的導熱性能和電氣絕緣性能。在-40°C~150°C可以穩定工作,滿足UL94V0的阻燃等級要求。

TP200 thermally conductive rubber pad is composed of silicone polymer and ceramic fillers. It is fabricated via special work man ship with high Cost performance value. It is double side self-tacky. Under low contact pressure, it can demonstrate excellent thermal transfer and electric isolation. Under -40—150°C, it performs stably and accords with UL94V0.



主要特性

- 導熱系數: 2.0W/mK
- 低壓縮力應用
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 容易裝配, 可重複使用

典型應用

- 計算器散熱模塊
- 冷卻器件到底盤或框架之間
- 高速大存儲驅動
- 汽車發動機控制單元
- 平面顯示器
- 功率轉換設備
- LED照明設備
- PDP顯示屏
- LCD背光模塊
- 網絡通信設備
- 電源模塊

MAIN CHARACTERISTICS

- Thermal Conductivity: 2.0W/m.k
- Low Compression application
- Double side in natural inherent tack
- Excellent electrical isolation
- Superior Temperature endurance
- Easy in assembly and reusable

APPLICATIONS

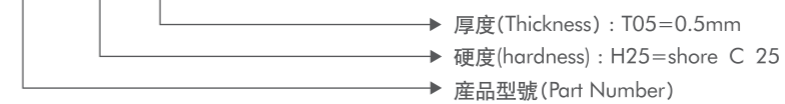
- Power electronics
- Power supply
- Mass storage devices
- Graphics card/processor/ASIC
- LED lighting
- Wire line/wireless communication shard ware
- Auto motive engine/trans mission controls
- Flat Panel Display(LCD、PDP、...)

TP200 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP200FG-T025	TP200-T05	TP200-T10	TP200-T20	TP200-T30	TP200-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.25	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	深灰色	深灰色	深灰色	深灰色	深灰色	深灰色	Visuai
硬度 Hardness (Shore C)	30±5	25±5	25±5	25±5	25±5	25±5	ASTM D2240
密度 Density (g/cm ³)	2.79	2.79	2.79	2.79	2.79	2.79	ASTM D792
撕裂強度 Tear strength (KN/m)	0.61	1.65	1.65	1.65	1.65	1.65	ASTM D412
延伸率 Elongation (%)	90	90	90	90	90	90	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	5.1	7.0	7.0	7.0	7.0	7.0	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	6×10 ¹²	6×10 ¹²	6×10 ¹²	6×10 ¹²	6×10 ¹²	6×10 ¹²	ASTM D257
介電常數 Dielectric constant (@1 MHz)	3.8	4.5	4.5	4.5	4.5	4.5	ASTM D150
重量損失 Weight loss (%)	<0.1	<0.1	<0.1	<0.1	<0.1	<0.1	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	2.0	2.0	2.0	2.0	2.0	2.0	ASTM D5470

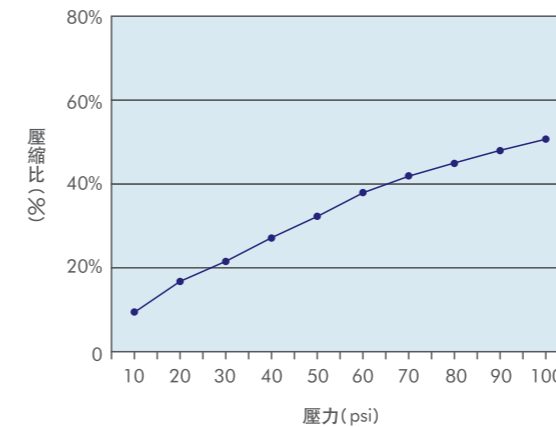
料號編碼原則 (Part Number Code) :

TP200/H25-T05

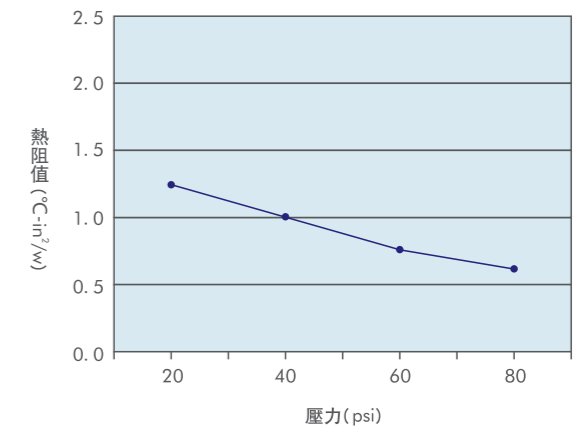


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

TP200/T20形變量與壓力關係圖



TP200/T20熱阻與壓力關係圖



TP250 導熱硅膠墊片 Thermal Conductive Pad

TP250系列導熱硅膠墊片, 配方獨特, 兼具成本效益與優異的導熱性能。雙面自粘, 與電子組件裝配使用時, 高壓縮力下表現出較低的熱阻和較好的電氣絕緣特性。在-40°C~150°C可以穩定工作, 滿足UL94V0的阻燃等級要求。

TP250 thermally conductive rubber pad is composed of silicone polymer and ceramic fillers. It is fabricated via special workmanship with high Cost/Performance value. It is double side self-tacky. Under low contact pressure, it can demonstrate excellent thermal transfer and electric isolation. Under -40~150°C, it performs stably and accords with UL94V0.



主要特性

- 導熱系數: 2.5W/mK
- 低壓縮力應用
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 兼具高散熱性能與成本效益

典型應用

- 筆記本和臺式計算機
- 顯卡內存
- 高導熱需求的模塊
- 冷卻器件到底□或框架之
- 高速大存儲驅動
- 汽車發動機控制單元
- 硬盤驅動和DVD驅動
- 功率轉換設備
- LCD背光模塊
- 網絡通信設備

MAIN CHARACTERISTICS

- Thermal conductivity: 2.5W/mK
- Low thermal resistance at very low pressures
- Conformable, low hardness
- Double side self-tacky
- high electrically isolative

APPLICATIONS

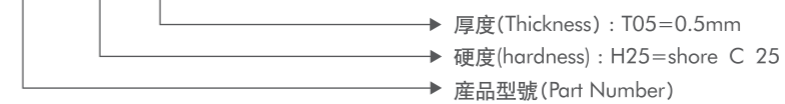
- PC/NB
- Processors to heat sinks
- GPU to heat sinks
- GPUVRAM
- Mass Storage Drives
- Auto motive engine/trans mission controls
- HD DVD driver IC
- Power conversion
- LCD back-light module
- Wire line/Wireless communication shard ware

TP250 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP250FG-T025	TP250-T05	TP250-T10	TP250-T20	TP250-T30	TP250-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.25	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	亮黃色	亮黃色	亮黃色	亮黃色	亮黃色	亮黃色	Visuai
硬度 Hardness (Shore C)	48	30±5	25±5	25±5	25±5	25±5	ASTM D2240
密度 Density (g/cm ³)	2.93	2.93	2.93	2.93	2.93	2.93	ASTM D792
撕裂強度 Tear strength (KN/m)	0.85	0.38	0.38	0.42	0.41	0.41	ASTM D412
延伸率 Elongation (%)	65	71	71	72	72	75	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	5.0	5.3	6.8	8.3	>10	>10	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	3.2×10 ¹⁶	3.2×10 ¹⁶	3.2×10 ¹⁶	3.2×10 ¹⁶	3.2×10 ¹⁶	3.2×10 ¹⁶	ASTM D257
介電常數 Dielectric constant (@1 MHz)	3.3	6.3	6.3	6.3	6.3	6.3	ASTM D150
重量損失 Weight loss (%)	<0.5	<0.5	<0.5	<0.5	<0.5	<0.5	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	2.5	2.5	2.5	2.5	2.5	2.5	ASTM D5470

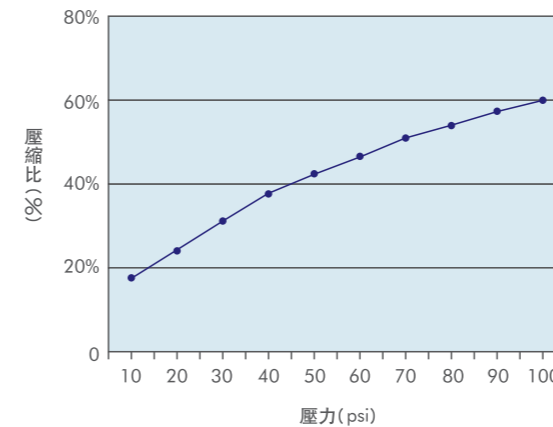
料號編碼原則 (Part Number Code) :

TP250/H25-T05

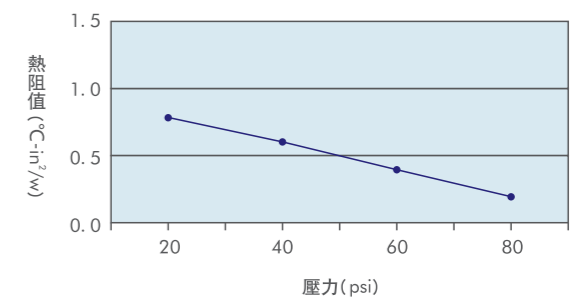


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

TP250/T20形變量與壓力關係圖



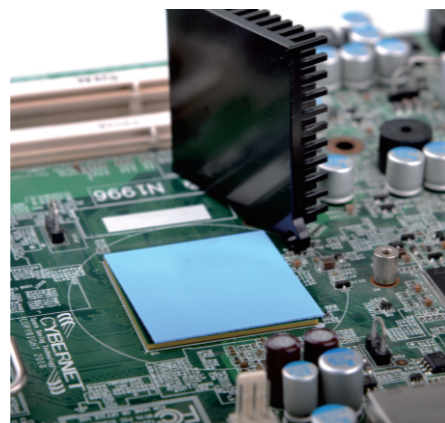
TP250/T20熱阻與壓力關係圖



TP300 導熱硅膠墊片 Thermal Conductive Pad

TP300是一款高導熱性能的材料，在低壓力的情況下表現出較小的熱阻。TP300具有自粘性，不需要額外的阻礙導熱的粘膠塗層。在-40°C~150°C可以穩定工作，同時滿足UL94V0等級阻燃要求。

The TP300 series is a superior thermal conductive pad. It is in low thermal resistance performance at low pressure. It has nature inherent tacky, it's required without extra glue coating for application. It works stably at ambient temperature during -40-150 celcius with meeting the requirement of UL94V-0 class.



主要特性

- 導熱系數: 3.0W/mK
- 低壓縮力應用
- 低壓縮力, 有高壓縮比
- 雙面自粘
- 高電氣絕緣
- 良好耐溫性能
- 兼具高散熱性能與成本效益

MAIN CHARACTERISTICS

- Thermal conductivity: 3.0W/mK
- Low thermal resistance at very low pressures
- Conformable, low hardness
- Double side self-tacky
- High electrically isolative

APPLICATIONS

- PC/NB and peripherals
- Processors to heat sinks
- GPU to heat sinks
- GPU/VRAM
- DRAM modules
- Heat Pipe assemblies
- CDROM/DVD cooling Mass Storage Drives
- Auto motive engine
- Trans mission controls Power conversion
- LCD back-light module
- Wire line/Wireless communication shard ware

典型應用

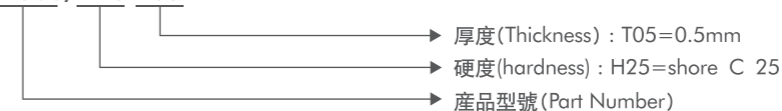
- 筆記本和臺式計算機
- 顯卡散熱模塊
- 高導熱需求的模塊
- 高速大存儲驅動
- 汽車發動機控制單元
- 硬盤驅動和DVD驅動
- LCD背光模塊
- 網絡通信設備

TP300 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP300FG-T025	TP300-T05	TP300-T10	TP300-T20	TP300-T30	TP300-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.25	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	亮藍色	亮藍色	亮藍色	亮藍色	亮藍色	亮藍色	Visuai
硬度 Hardness (Shore C)	45	30±5	25±5	25±5	25±5	25±5	ASTM D2240
密度 Density (g/cm ³)	2.9	2.7	2.7	2.7	2.7	2.7	ASTM D792
撕裂強度 Tear strength (KN/m)	0.92	0.29	0.32	0.33	0.31	0.31	ASTM D412
延伸率 Elongation (%)	60	63	63	63	64	64	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	4.5	4.8	6.8	8.5	>10	>10	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	1.1×10 ¹⁶	1.1×10 ¹⁶	1.1×10 ¹⁶	1.1×10 ¹⁶	1.1×10 ¹⁶	1.1×10 ¹⁶	ASTM D257
介電常數 Dielectric constant (@1 MHz)	3.96	7.15	7.15	7.15	7.15	7.15	ASTM D150
重量損失 Weight loss (%)	<0.3	<0.3	<0.3	<0.3	<0.3	<0.3	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	3.0	3.0	3.0	3.0	3.0	3.0	ASTM D5470

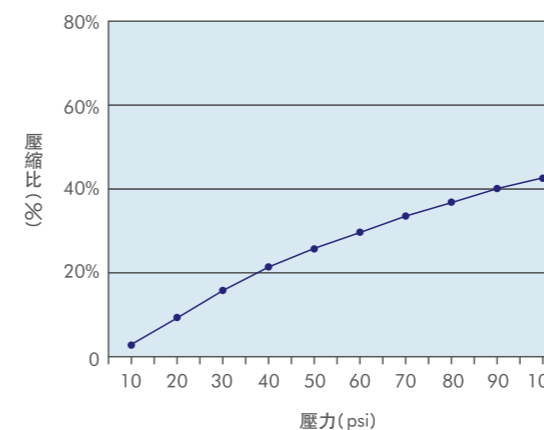
料號編碼原則 (Part Number Code) :

TP300/H25-T05

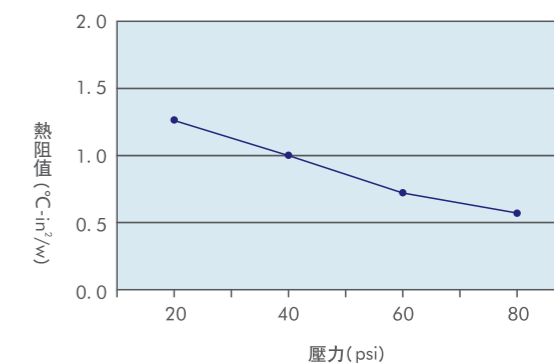


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

TP300/T20形變量與壓力關係圖



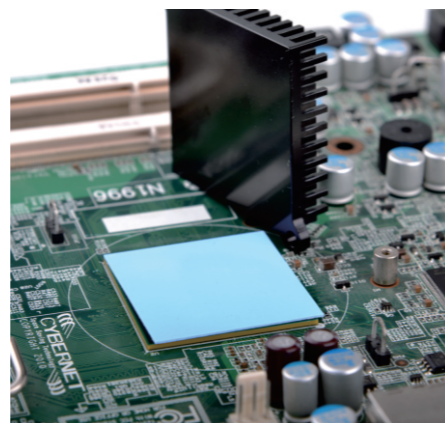
TP300/T20熱阻與壓力關係圖



TP400 導熱硅膠墊片 Thermal Conductive Pad

TP400系列導熱硅膠墊片,是一款高導熱性能的材料,雙面自粘,與電子組件裝配使用時,低壓縮力下表現出較低的熱阻和較好的電氣絕緣特性。在-40°C~150°C可以穩定工作,滿足UL94V0的阻燃等級要求。

TP400 thermally conductive rubber pad is composed of silicone polymer and ceramic fillers.It is fabricated via special work man ship with high Cost performance value.It is double side self-tacky.Under low contact pressure,it can demonstrate excellent thermal transfer and electric isolation.Under-40—150°C,it performs stably and accords with UL94V0.



主要特性

- 導熱系數:4.0W/mK
- 低壓縮力應用
- 低壓縮力,有高壓縮比
- 雙面自粘
- 低出油
- 高電氣絕緣
- 良好耐溫性能
- 兼具高散熱性能與成本效益

典型應用

- 筆記本和臺式計算機
- 顯卡散熱模塊
- 高導熱需求的模塊
- 高速大存儲驅動
- 汽車發動機控制單元
- 硬盤驅動和DVD驅動
- LCD背光模塊
- 網絡通信設備

MAIN CHARACTERISTICS

- Thermal conductivity:4.0W/mK
- Low thermal resistance at very low pressures
- Conformable,low hardness
- Double side self-tacky
- High electrically isolative

APPLICATIONS

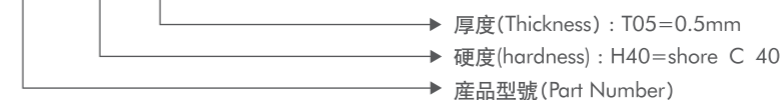
- PC/NB and peripherals
- Processors to heat sinks
- GPU to heat sinks GPUVRAM DRAM modules
- Heat Pipe assemblies
- Power conversion
- Wire line/Wireless communication shard ware
- LCD back-light module

TP400 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP400-T05	TP400-T10	TP400-T20	TP400-T30	TP400-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	淺藍色	淺藍色	淺藍色	淺藍色	淺藍色	Visual
硬度 Hardness (Shore C)	40	40	40	40	40	ASTM D2240
密度 Density (g/cm ³)	3.15	3.15	3.15	3.15	3.15	ASTM D792
撕裂強度 Tear strength (KN/m)	0.90	0.90	0.12	0.12	0.12	ASTM D412
延伸率 Elongation (%)	11	11	11	20	20	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	6.1	6.3	7.4	7.5	7.5	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	1.0×10 ¹²	1.0×10 ¹²	1.0×10 ¹²	1.0×10 ¹²	1.0×10 ¹²	ASTM D257
介電常數 Dielectric constant (@1 MHz)	5.5	5.5	5.5	5.5	5.5	ASTM D150
重量損失 Weight loss (%)	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	4.0	4.0	4.0	4.0	4.0	ASTM D5470

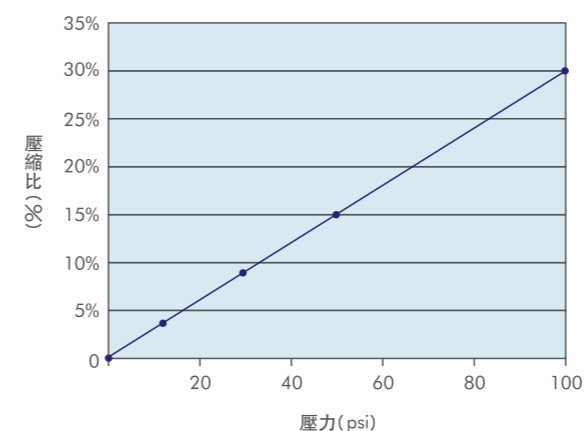
料號編碼原則 (Part Number Code) :

TP400/H40-T05

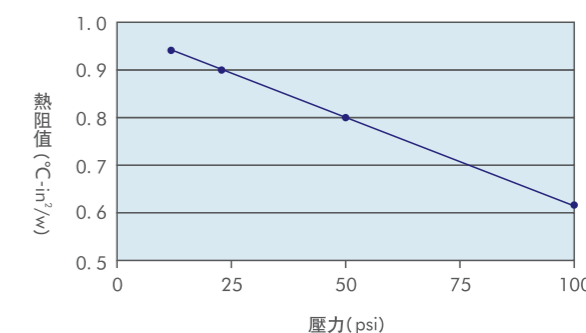


標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

TP400-T20形變量與壓力關係圖



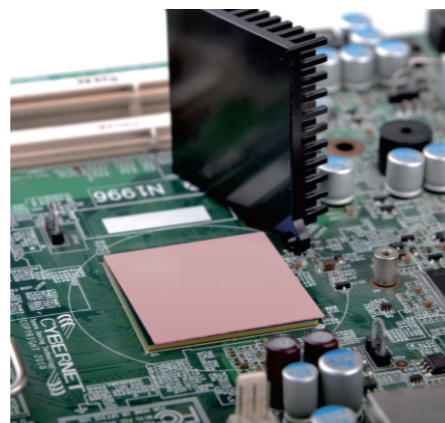
TP400-T20形變量與壓力關係圖



TP600 導熱硅膠墊片 Thermal Conductive Pad

TP600系列導熱硅膠墊片,是一款高導熱性能的材料,雙面自粘,與電子組件裝配使用時,低壓縮力下表現出較低的熱阻和較好的電氣絕緣特性。在-40°C~150°C可以穩定工作,滿足UL94V0的阻燃等級要求。

TP600 thermally conductive rubber pad is composed of silicone polymer and ceramic fillers. It is fabricated via special work man ship with high Cost performance value. It is double side self-tacky. Under low contact pressure, it can demonstrate excellent thermal transfer and electric isolation. Under -40—150°C, it performs stably and accords with UL94V0.



主要特性

- 導熱系數: 6.0W/mK
- 低壓縮力應用
- 低壓縮力, 有高壓縮比
- 雙面自粘
- 低出油, 高電氣絕緣
- 良好耐溫性能兼具高散熱性能與成本效益

典型應用

- 筆記本和臺式計算機
- 顯卡散熱模塊
- 高導熱需求的模塊
- 高速大存儲驅動
- 汽車發動機控制單元
- 硬盤驅動和DVD驅動
- LCD背光模塊
- 網絡通信設備

MAIN CHARACTERISTICS

- Thermal conductivity: 6.0W/mK
- Low thermal resistance at very low pressures
- Conformable, low hardness
- Double side self-tacky
- High electrically isolative

APPLICATIONS

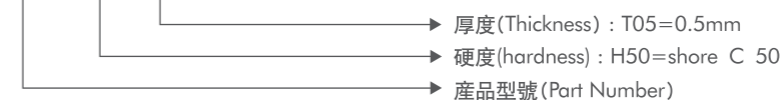
- PC/NB and peripherals
- Processors to heat sinks
- GPU to heat sinks DRAM modules
- Heat Pipe assemblies
- Thermally-enhanced BG As High-power power supply
- PCBA to housing
- Auto motive engine/transmission controls
- Wire line/Wireless communication shard ware

TP600 導熱硅膠墊片 Thermal Conductive Pad

特性 Properties	TP600-T05	TP600-T10	TP600-T20	TP600-T30	TP600-T40	測試方法 TEST METHOD
厚度 Thickness (mm)	0.5	1.0	2.0	3.0	4.0	ASTM D374
組成成份 Composition	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	硅膠&陶瓷	—
顏色 Color	紅灰色	紅灰色	紅灰色	紅灰色	紅灰色	Visual
硬度 Hardness (Shore C)	50	50	50	50	50	ASTM D2240
密度 Density (g/cm ³)	3.5	3.5	3.5	3.5	3.5	ASTM D792
撕裂強度 Tear strength (KN/m)	1.0	1.0	1.0	1.0	1.0	ASTM D412
延伸率 Elongation (%)	80	80	80	80	80	ASTM D374
耐溫範圍 Operation temperature (°C)	-40—150	-40—150	-40—150	-40—150	-40—150	EN344
擊穿電壓 Breakdown voltage (Kv)	>6	>6	>6	>6	>6	ASTM D149
體積電阻率 Volume resistivity (Ω·cm)	1.0×10 ¹³	1.0×10 ¹³	1.0×10 ¹³	1.0×10 ¹³	1.0×10 ¹³	ASTM D257
介電常數 Dielectric constant (@1 MHz)	6.4	6.4	6.4	6.4	6.4	ASTM D150
重量損失 Weight loss (%)	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5	@200°C240H
防火性能	V-0	V-0	V-0	V-0	V-0	UL 94
導熱系數 Thermal conductivity (W/m·K)	6.0	6.0	6.0	6.0	6.0	ASTM D5470

料號編碼原則 (Part Number Code) :

TP600/H50-T05



標準尺寸 (standard size) : 200mm×400mm, 可依客戶指定模切成各種尺寸或形狀。(Custom-made in regular or irregular dimensions) 0.25mm產品使用玻纖加強, 產品名稱以“FG”后綴。

